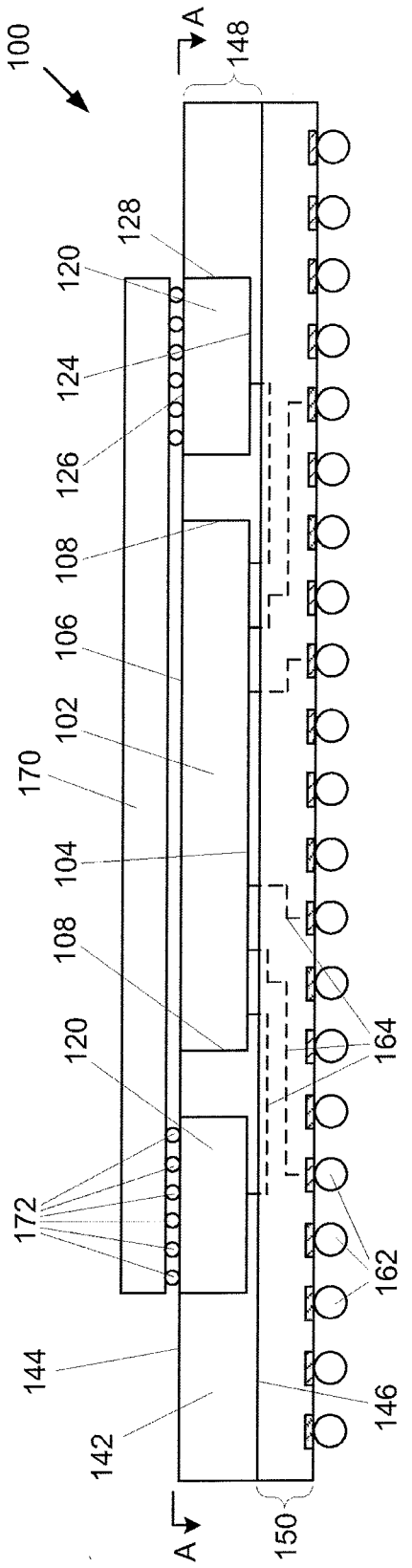

100
A
148
128
120
124
126
108
106
102
170
104
108
120
164
172
162
144
146
142
150
A

FIG. 1

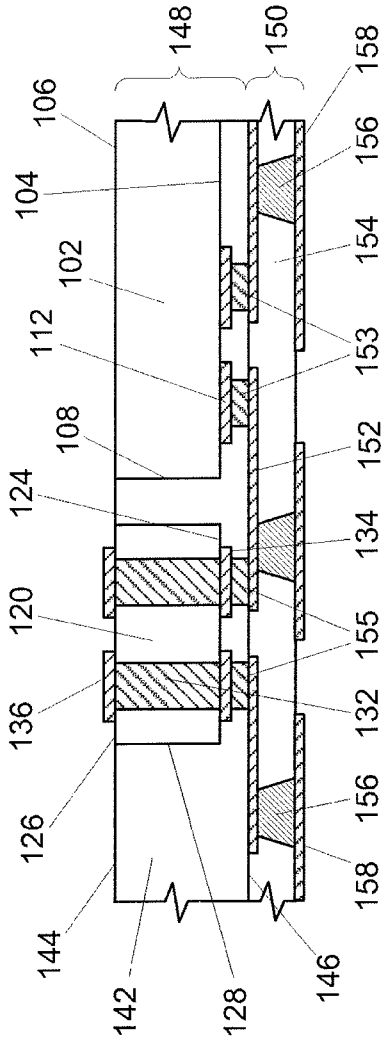

148
150
158
106
156
104
154
102
153
112
152
108
134
124
155
120
132
136
156
126
158
144
142
128
146

FIG. 2

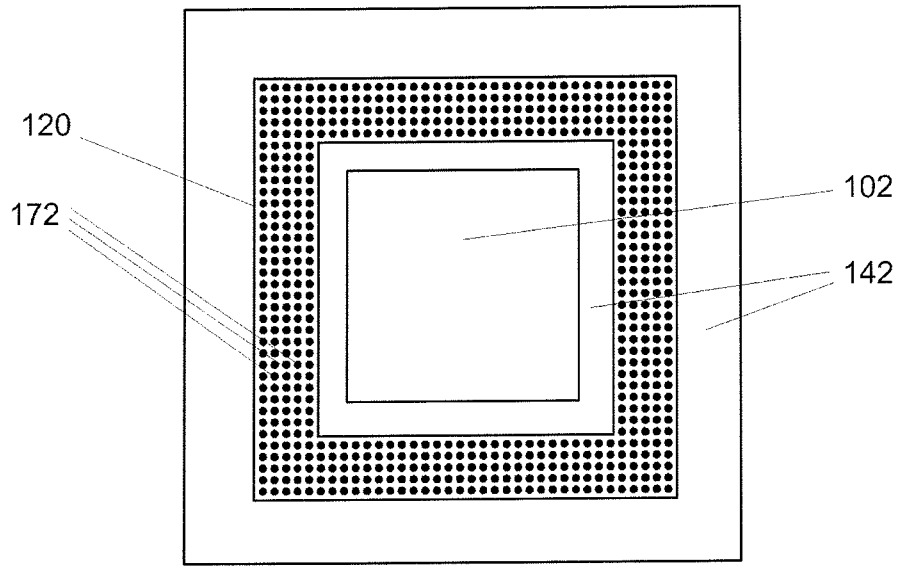


FIG. 3

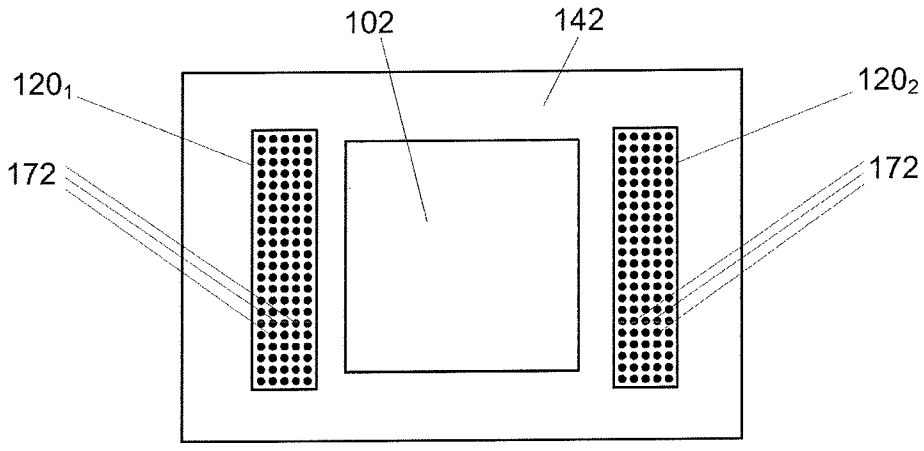


FIG. 4

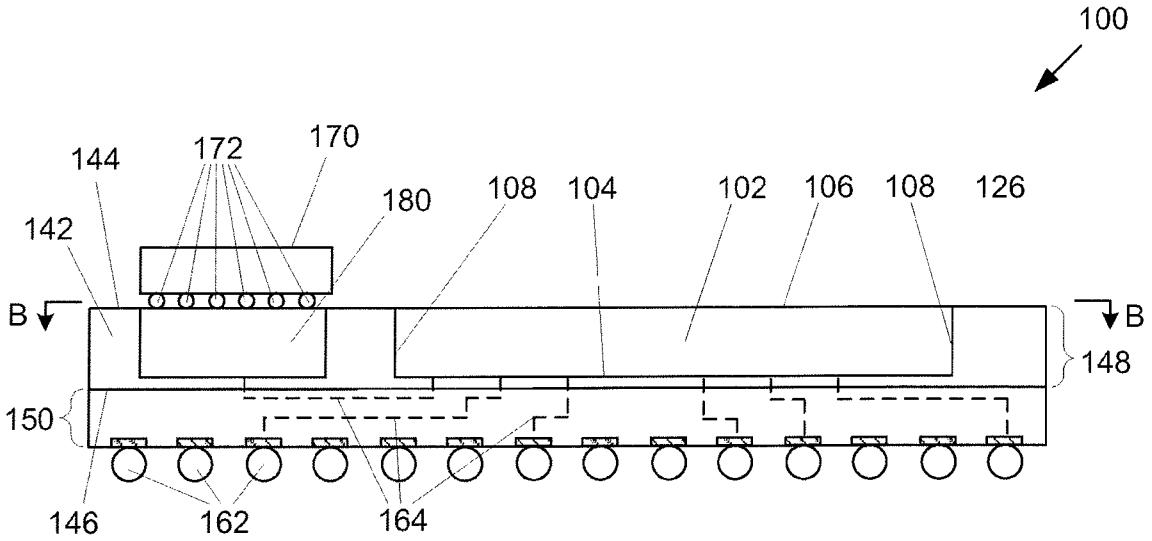

100
144
172
170
180
108
104
102
106
108
126
142
B
B
148
150
146
162
164

FIG. 5

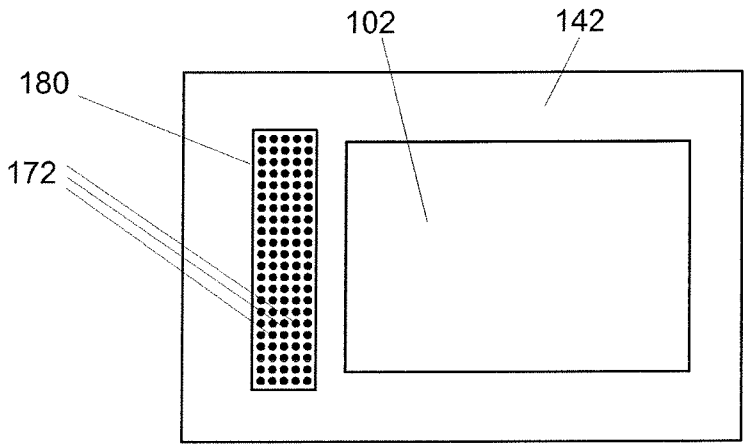

102
142
180
172

FIG. 6

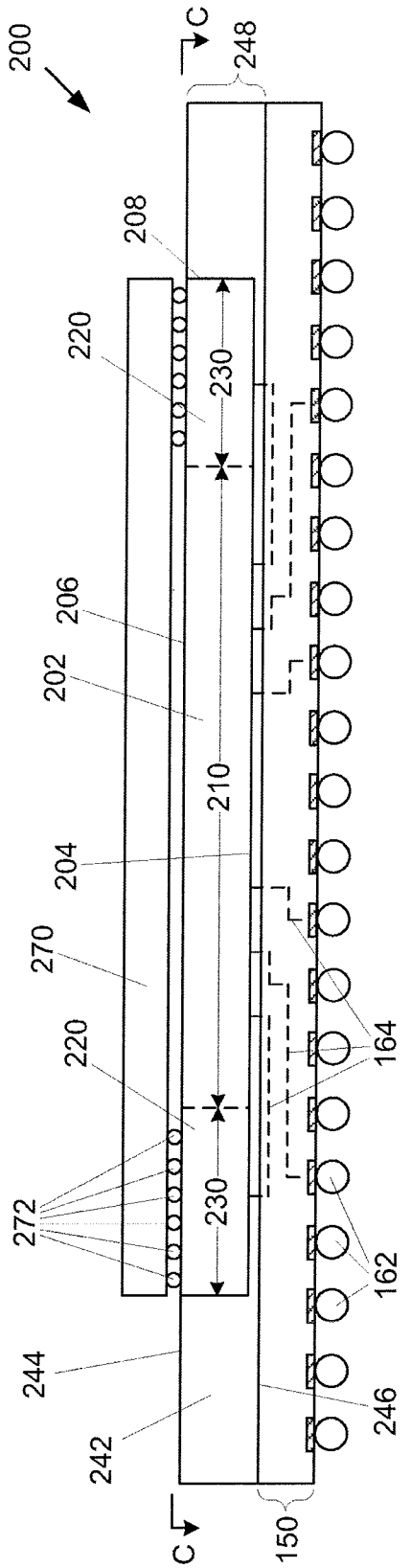

200
C
248
208
220
230
206
202
210
204
270
220
164
272
230
162
244
246
242
150
C

FIG. 7

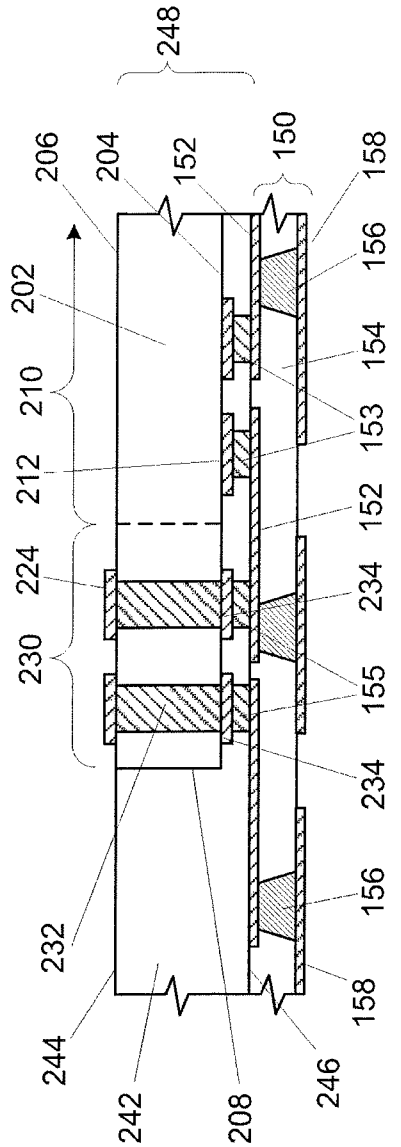

248
206
204
152
150
158
156
202
154
210
153
212
152
224
234
230
155
234
232
156
158
244
242
208
246

FIG. 8

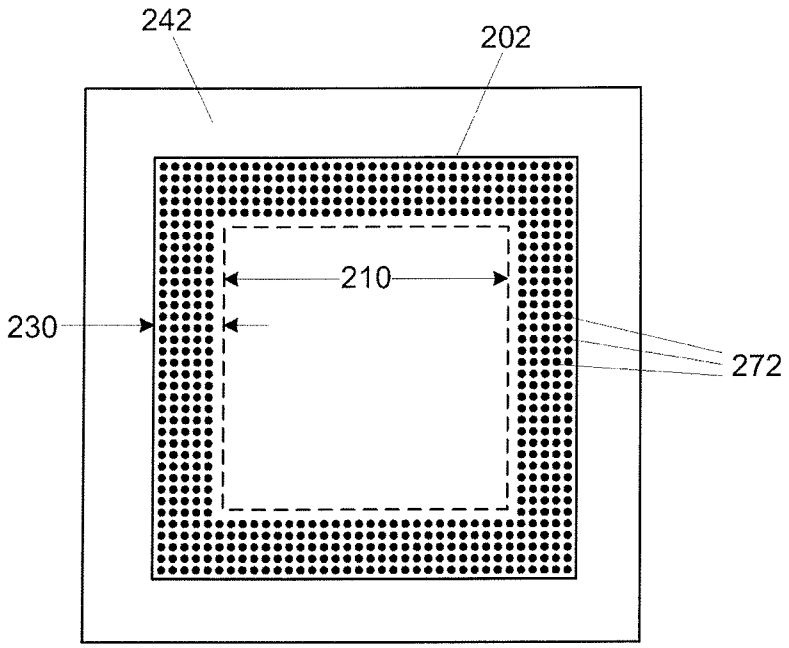


FIG. 9

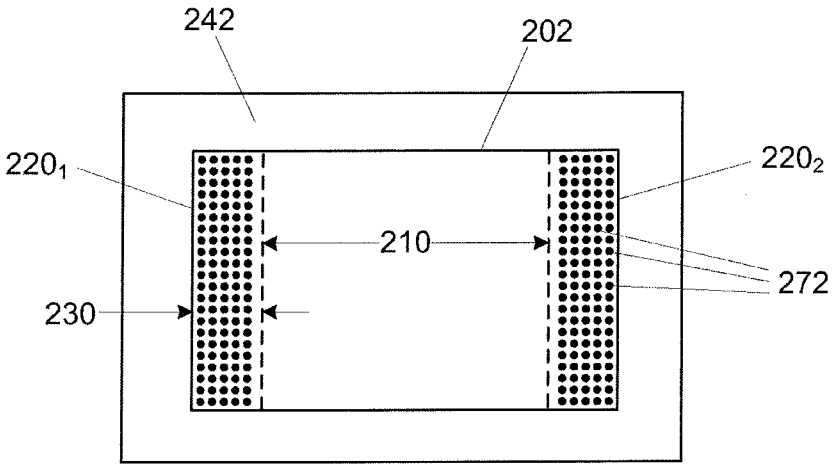


FIG. 10

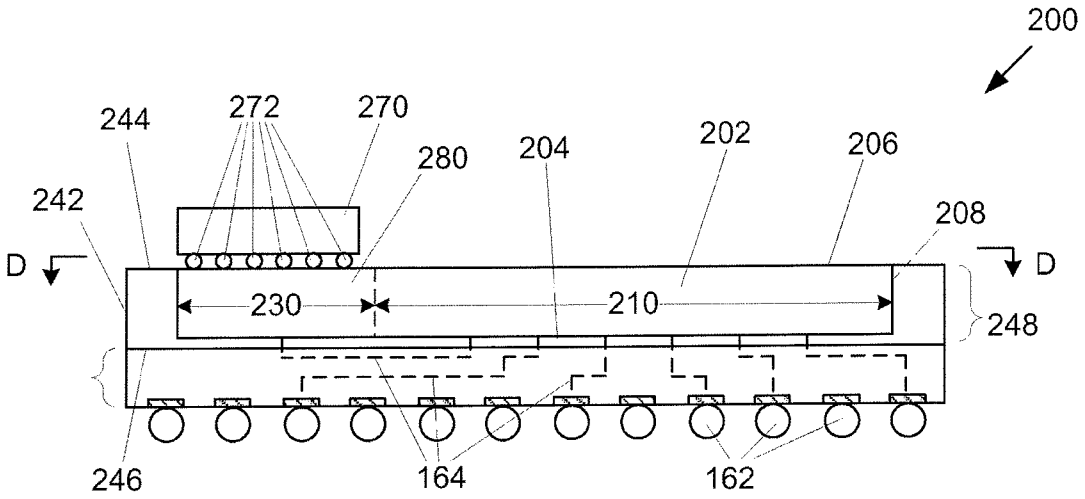

200
244
272
270
280
204
202
206
242
208
D
D
230
210
248
246
164
162

FIG. 11

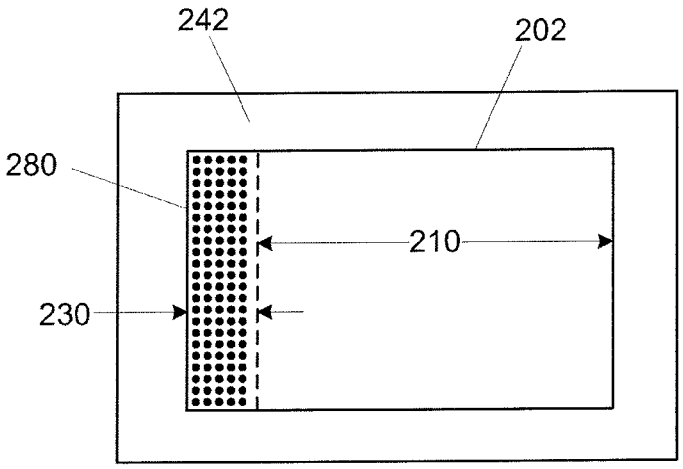

242
202
280
210
230

FIG. 12

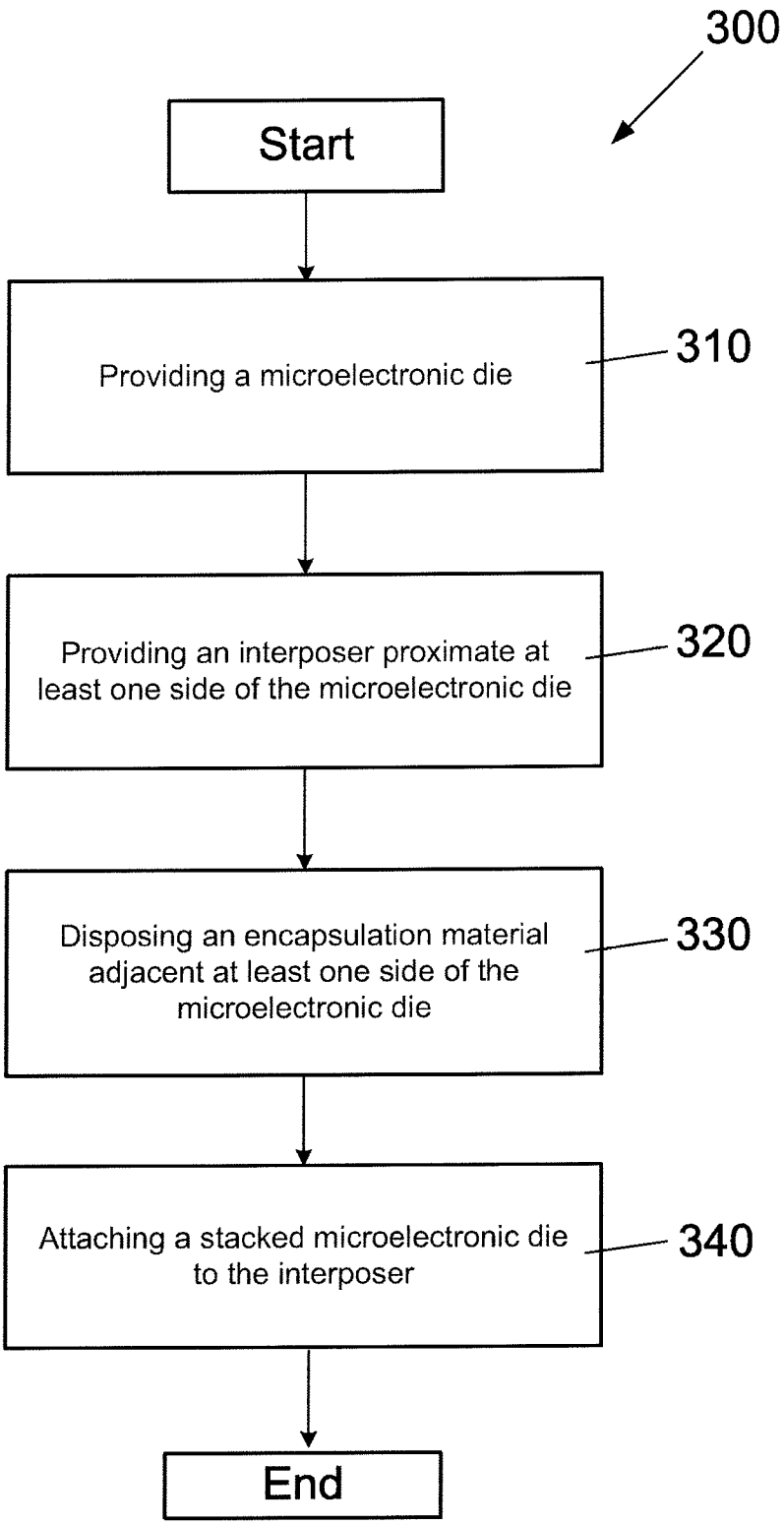

300
Start
Providing a microelectronic die
310
Providing an interposer proximate at least one side of the microelectronic die
320
Disposing an encapsulation material adjacent at least one side of the microelectronic die
330
Attaching a stacked microelectronic die to the interposer
340
End

FIG. 13